# **MAX2057**

#### **ABSOLUTE MAXIMUM RATINGS**

V <sub>CC</sub> to GND	0.3V to +5.5V
V <sub>CNTL</sub> to GND (with V <sub>CC</sub> applied)	0V to 4.75V
Current into V <sub>CNTL</sub> pin (V <sub>CC</sub> grounded)	40mA
All Other Pins to GND0	.3V to $(V_{CC} + 0.3V)$
RF Input Power (IN, IN_A, ATTN_OUT, OUT_	_A)+20dBm
RF Input Power (AMP_IN)	+12dBm
θ <sub>JA</sub> (natural convection)	35°C/W
$\theta_{JA}$ (1m/s airflow)	31°C/W

θ <sub>JA</sub> (2.5m/s airflow)	
θ <sub>JC</sub> (junction to exposed pad)	10°C/W
Operating Temperature Range	40°C to +85°C
Storage Temperature Range	65°C to +150°C
Junction Temperature	+150°C
Lead Temperature (soldering, 10s)	+300°C
Soldering Temperature (reflow)	+260°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## DC ELECTRICAL CHARACTERISTICS

 $(V_{CC} = +4.75V \text{ to } +5.25V, \text{ no RF signals applied, all input and output ports terminated with 50\Omega, T_A = -40°C \text{ to } +85°C, unless otherwise noted. Typical values are at V_{CC} = +5.0V, T_A = +25°C, unless otherwise noted.)$ 

PARAMETER	CONDITIONS	MIN	ТҮР	MAX	UNITS
Supply Voltage		4.75	5	5.25	V
Supply Current	R1 = $1.2k\Omega$ , R2 = $2k\Omega$ (Note 1)		180	230	mA
R <sub>SET1</sub> Current	$R1 = 1.2k\Omega \text{ (Note 1)}$		1		mA
R <sub>SET2</sub> Current	$R1 = 2k\Omega$ (Note 1)		0.6		mA
Gain-Control Voltage Range	(Note 2)	1.0		4.5	V
Gain-Control Pin Input Resistance	$V_{CNTL} = 1V \text{ to } 4.5V$	50			kΩ

## **RECOMMENDED AC OPERATING CONDITIONS**

PARAMETER	CONDITIONS	MIN	ТҮР	MAX	UNITS
Frequency Range	(Note 3)	1300		2700	MHz

## AC ELECTRICAL CHARACTERISTICS

(Typical Operating Circuit with one attenuator connected,  $V_{CC} = +4.75V$  to +5.25V,  $T_A = -40^{\circ}C$  to  $+85^{\circ}C$ ,  $f_{|N} = 1700MHz$  to 2500MHz, unless otherwise noted. Typical values are at  $V_{CC} = +5.0V$ ,  $R1 = 1.2k\Omega$ ,  $R2 = 2k\Omega$ ,  $P_{OUT} = +5dBm$ ,  $f_{|N} = 2100MHz$ ,  $V_{CNTL} = 1V$ ,  $50\Omega$  system impedance, second attenuator is not connected,  $T_A = +25^{\circ}C$ , unless otherwise noted.) (Note 4)

PARAMETER	CONE	DITIONS	MIN	ТҮР	MAX	UNITS	
	$T_A = +25^{\circ}C, V_{CC} = 5.0V, f_{IN}$	$T_A = +25^{\circ}C, V_{CC} = 5.0V, f_{IN} = 2100MHz$		15.5	17.5		
Gain	$T_A = +25^{\circ}C, V_{CC} = 5.0V, f_{IN}$	<sub>N</sub> = 1560MHz	11.5	14.5	16.5	dB	
Gain	$T_A = +25^{\circ}C, V_{CC} = 5.0V, f_{IN}$	<sub>N</sub> = 1500MHz	11.5	14.3	16.5		
	$T_A = +25^{\circ}C, V_{CC} = 5.0V, f_{IN}$	<sub>N</sub> = 1450MHz	11.5	14	16.5		
		$V_{CNTL} = 1V$		+0.9			
	$T_{A} = +25^{\circ}C \text{ to } -40^{\circ}C$	$V_{CNTL} = 1.8V$		+0.41			
	IA = +25 C 10 - 40 C	$V_{CNTL} = 2.6V$		+0.09			
		$V_{CNTL} = 3.5V$		-0.16		dB	
Maximum Gain Variation		$V_{CNTL} = 1V$		-1			
	$T_{A} = +25^{\circ}C \text{ to } +85^{\circ}C$	$V_{CNTL} = 1.8V$	V <sub>CNTL</sub> = 1.8V -0.56			]	
	$I_A = +25 \cup 10 + 65 \cup$	$V_{CNTL} = 2.6V$		-0.32			
		$V_{CNTL} = 3.5V$		+0.1			

## AC ELECTRICAL CHARACTERISTICS (continued)

(Typical Operating Circuit with one attenuator connected,  $V_{CC} = +4.75V$  to +5.25V,  $T_A = -40^{\circ}C$  to  $+85^{\circ}C$ ,  $f_{IN} = 1700$ MHz to 2500MHz, unless otherwise noted. Typical values are at  $V_{CC} = +5.0V$ ,  $R1 = 1.2k\Omega$ ,  $R2 = 2k\Omega$ ,  $P_{OUT} = +5dBm$ ,  $f_{IN} = 2100$ MHz,  $V_{CNTL} = 1V$ ,  $50\Omega$  system impedance, second attenuator is not connected,  $T_A = +25^{\circ}C$ , unless otherwise noted.) (Note 3)

PARAMETER	CONDITIONS			ТҮР	MAX	UNITS
Reverse Isolation				37		dB
Noise Figure	(Note 5)			6		dB
Output 1dB Compression Point				+23.8		dBm
Output 2nd-Order Intercept Point	From maximum gain to 15dB $f_1 + f_2$ (Note 6)	attenuation, measured at		+64		dBm
Output 3rd-Order Intercept Point	From maximum gain to 15dB	attenuation (Note 5)		+37		dBm
Output 3rd-Order Intercept Point	T <sub>A</sub> = +25°C to +85°C			-0.83		alD
Variation Over Temperature	$T_A = +25^{\circ}C \text{ to } -40^{\circ}C$			-0.6		dB
2nd Harmonic	From maximum gain to 15dB a	attenuation, $P_{OUT} = +5dBm$		-65		dBc
3rd Harmonic	From maximum gain to 15dB a	attenuation, $P_{OUT} = +5 dBm$		-83		dBc
	$f_{IN} = 1700 MHz$ to 2200MHz,	One attenuator	17	20.7		
RF Gain-Control Range	$V_{CNTL} = 1V$ to $4V$	Two attenuators	34	42.4		dB
nr Gain-Control hange	$f_{IN} = 1450MHz$ to 1560MHz, V <sub>CNTL</sub> = 1V to 4V	One attenuator	17	22		
		Two attenuators	34	44		
RF Gain-Control Slope	$V_{CNTL} = 1.8V$ to $3.5V$			-10		dB/V
Maximum RF Gain-Control Slope	Maximum slope vs. gain-con	Maximum slope vs. gain-control voltage		-15.2		dB/V
Gain Flatness Over 100MHz Bandwidth	Peak-to-peak for all settings			0.5		dB
Attenuator Switching Time	15dB attenuation change (No	te 7)		500		ns
Attenuator Insertion Loss	Second attenuator (IN_A, OUT	[_A)		2.2		dB
Input Return Loss	Entire band, all gain settings			18		dB
Output Return Loss	Entire band, all gain settings			15		dB
Group Delay	Input/output 50 $\Omega$ lines de-em	bedded		300		ps
Group Delay Flatness Over 100MHz Bandwidth	Peak to peak			20		ps
Group Delay Change vs. Gain Control	$V_{CNTL} = 1V$ to $4V$			-70		ps
Insertion Phase Change vs. Gain Control	$V_{CNTL} = 1V$ to $4V$			50		degrees

Note 1: Total supply current reduces as  $R_1$  and  $R_2$  are increased.

Note 2: Operating outside this range for extended periods may affect device reliability. Limit pin input current to 40mA when V<sub>CC</sub> is not present.

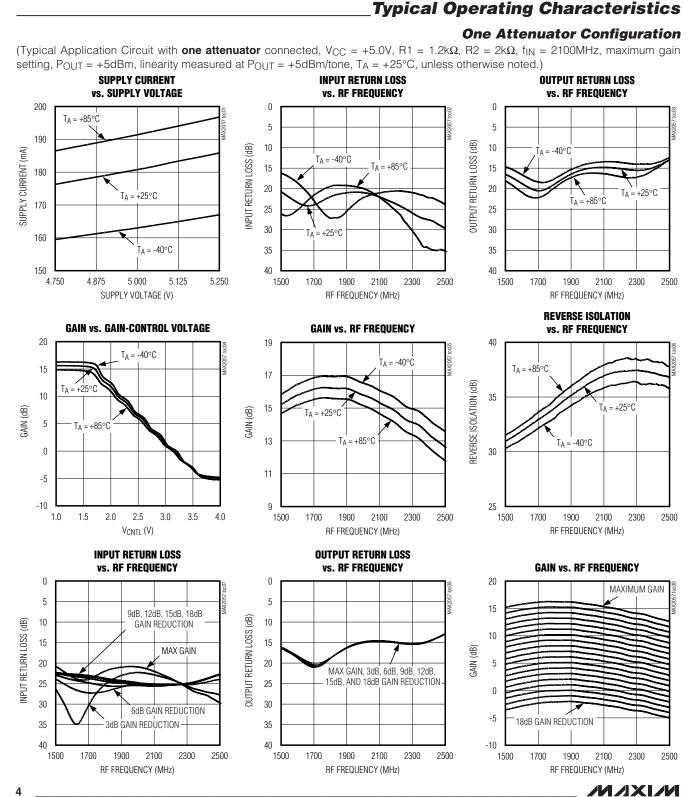
**Note 3:** Operation outside this range is possible, but with degraded performance of some parameters.

Note 4: All limits include external component losses, unless otherwise noted.

**Note 5:** Noise figure increases by approximately 1dB for every 1dB of gain reduction.

**Note 6:** f<sub>1</sub> = 2100MHz, f<sub>2</sub> = 2101MHz, +5dBm/tone at OUT.

Note 7: Switching time is measured from 50% of the control signal to when the RF output settles to ±1dB.



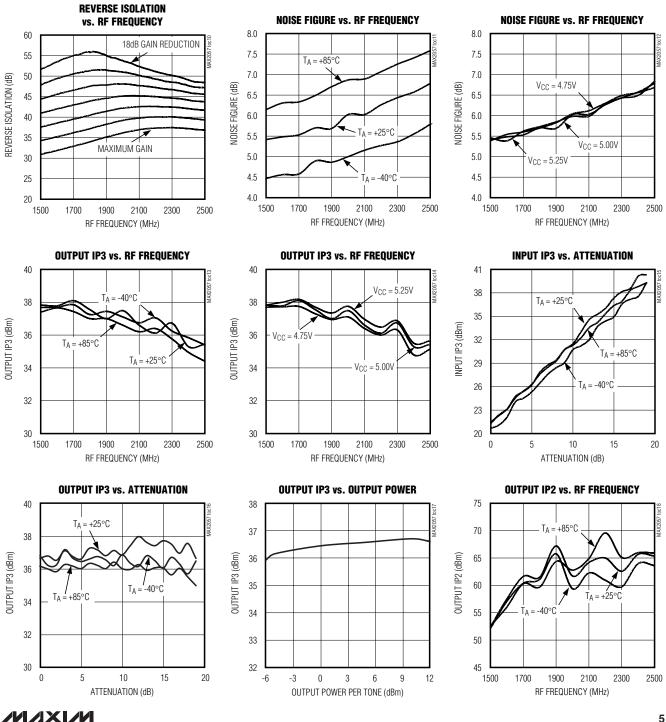
**MAX2057** 

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## **Typical Operating Characteristics (continued)**

#### **One Attenuator Configuration**

(Typical Application Circuit with one attenuator connected,  $V_{CC} = +5.0V$ ,  $R1 = 1.2k\Omega$ ,  $R2 = 2k\Omega$ ,  $f_{IN} = 2100MHz$ , maximum gain setting,  $P_{OUT} = +5dBm$ , linearity measured at  $P_{OUT} = +5dBm/tone$ ,  $T_A = +25^{\circ}C$ , unless otherwise noted.)



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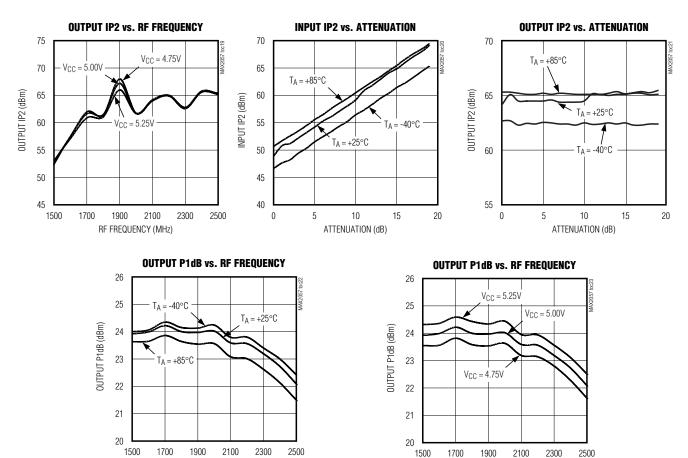
RF FREQUENCY (MHz)

## **Typical Operating Characteristics (continued)**

RF FREQUENCY (MHz)

#### **One Attenuator Configuration**

(Typical Application Circuit with **one attenuator** connected,  $V_{CC} = +5.0V$ , R1 =  $1.2k\Omega$ , R2 =  $2k\Omega$ ,  $f_{IN} = 2100MHz$ , maximum gain setting,  $P_{OUT} = +5dBm$ , linearity measured at  $P_{OUT} = +5dBm$ /tone,  $T_A = +25^{\circ}C$ , unless otherwise noted.)

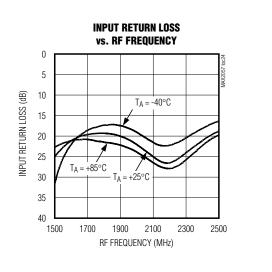


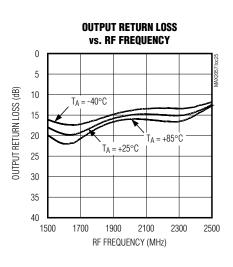
**MAX2057** 

## **Typical Operating Characteristics**

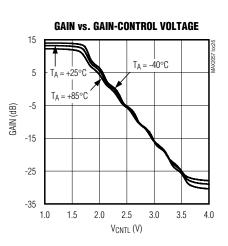
#### **Two Attenuator Configuration**

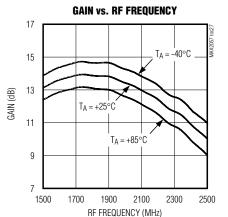
(Typical Application Circuit with **two attenuators** connected,  $V_{CC} = +5.0V$ ,  $R1 = 1.2k\Omega$ ,  $R2 = 2k\Omega$ ,  $f_{IN} = 2100MHz$ , maximum gain setting,  $P_{OUT} = +5dBm$ , linearity measured at  $P_{OUT} = +5dBm$ /tone,  $T_A = +25^{\circ}C$ , unless otherwise noted.)







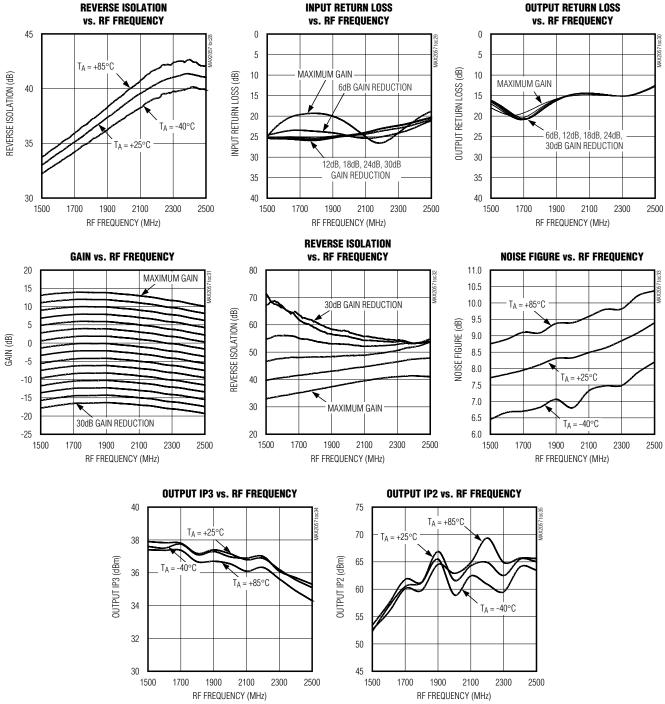




## **Typical Operating Characteristics (continued)**

#### **Two Attenuator Configuration**

(Typical Application Circuit with **two attenuators** connected,  $V_{CC} = +5.0V$ ,  $R1 = 1.2k\Omega$ ,  $R2 = 2k\Omega$ ,  $f_{IN} = 2100MHz$ , maximum gain setting,  $P_{OUT} = +5dBm$ , linearity measured at  $P_{OUT} = +5dBm$ /tone,  $T_A = +25^{\circ}C$ , unless otherwise noted.)



**MAX2057** 

## Pin Description

PIN	NAME	FUNCTION
1, 3, 4, 6, 7, 9, 10, 12, 14, 18, 19, 21–24, 27, 28, 30, 31, 33, 34, 36	GND	Ground. Connect to the board's ground plane using low-inductance layout techniques.
2	OUT_A	Second-Attenuator Output. Internally matched to $50\Omega$ over the operating frequency band. Connect to IN through a DC-blocking capacitor if greater than 21dB of gain-control range is required. No connection is required if the second attenuator is not used.
5, 13, 16, 25, 32	V <sub>CC</sub>	Power Supply. Bypass each pin to GND with capacitors as shown in the <i>Typical Application Circuit</i> . Place capacitors as close to the pin as possible.
8	IN_A	Second-Attenuator Input. Internally matched to $50\Omega$ over the operating frequency band. Connect to a $50\Omega$ RF source through a DC-blocking capacitor if greater than 21dB of gain-control range is required. No connection is required if the second attenuator is not used.
11	VCNTL	Analog Gain-Control Input. Limit voltages applied to this pin to a 1V to 4.5V range when V <sub>CC</sub> is present to ensure device reliability.
15	R <sub>SET1</sub>	First-Stage Amplifier Bias-Current Setting. Connect to GND through a 1.2k $\Omega$ resistor.
17	R <sub>SET2</sub>	Second-Stage Amplifier Bias-Current Setting. Connect to GND through a $2k\Omega$ resistor.
20	OUT	RF Output. Internally matched to $50\Omega$ over the operating frequency band. Requires a DC-blocking capacitor and a shunt-matching capacitor.
26	AMP_IN	Amplifier Input. Internally matched to $50\Omega$ over the operating frequency band. Connect to ATTN_OUT through a DC-blocking capacitor.
29	ATTN_OUT	Attenuator Output. Internally matched to $50\Omega$ over the operating frequency band. Connect to AMP_IN through a DC-blocking capacitor.
35	IN	RF Input. Internally matched to $50\Omega$ over the operating frequency band. Connect to a $50\Omega$ RF source through a DC-blocking capacitor if the second attenuator is not used.
_	EP	Exposed Pad. This pad affects RF performance and provides heat dissipation. This pad <b>MUST</b> be soldered evenly to the board's ground plane for proper operation.

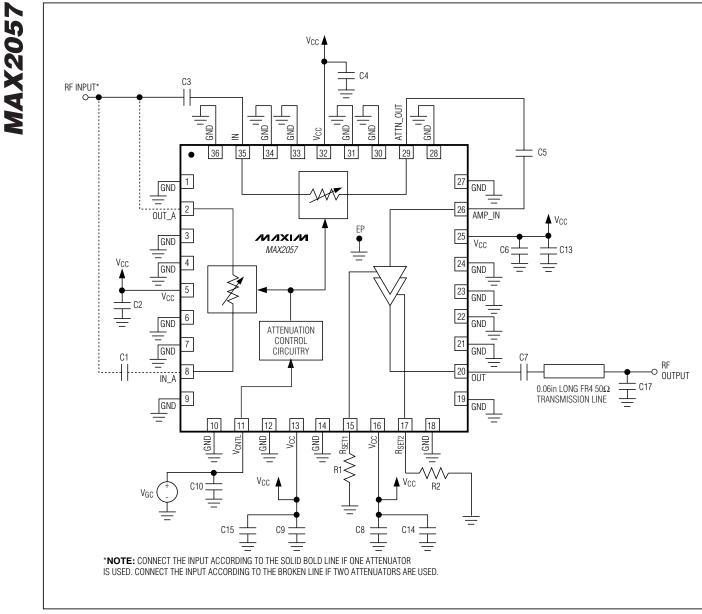


Figure 1. Typical Application Circuit

#### **Detailed Description**

The MAX2057 general-purpose, high-performance VGA with analog gain control is designed to interface with 50  $\Omega$  systems operating in the 1300MHz to 2700MHz frequency range.

The MAX2057 integrates two attenuators to provide 21dB or 42dB of precision analog gain control, as well

as a two-stage amplifier that has been optimized to provide high gain, high IP3, low noise figure, and low power consumption. The bias current of each amplifier stage can be adjusted by individual external resistors to further reduce power consumption for applications that do not require high linearity.



# Table 1. Typical Application CircuitComponent Values

DESIGNATION	VALUE	ТҮРЕ
C1, C3, C5, C7, C10	22pF	Microwave capacitors (0402)
C2, C4, C6, C8, C9	1000pF	Microwave capacitors (0402)
C13, C14, C15	0.1µF	Microwave capacitors (0603)
C17	0.75pF	Microwave capacitor (0402)
R1	1.2kΩ	±1% resistor (0402)
R2	2kΩ	±1% resistor (0402)

## **Applications Information**

#### **Analog Attenuation Control**

A single input voltage at the V<sub>CNTL</sub> pin adjusts the gain of the MAX2057. Up to 21dB of gain-control range is provided through a single attenuator. At the maximum gain setting, each attenuator's insertion loss is approximately 2.2dB. With the single attenuator at the maximum gain setting, the device provides a nominal 15.5dB of cascaded gain and 6dB of cascaded noise figure.

If a larger gain-control range is desired, a second onchip attenuator can be connected in the signal path to provide an additional 21dB of gain-control range. With the second attenuator connected at the maximum gain setting, the device typically exhibits 13.3dB of cascaded gain. Note that the V<sub>CNTL</sub> pin simultaneously adjusts both on-chip attenuators.

The V<sub>CNTL</sub> input voltage drives a high-impedance load (>  $50k\Omega$ ). It is suggested that a current-limiting resistor be included in series with this connection to limit the input current to less than 40mA should the control voltage be applied when V<sub>CC</sub> is not present. A series resistor of greater than  $200\Omega$  will provide complete protection for 5V control voltage ranges. Limit V<sub>CNTL</sub> input voltages to a 1.0V to 4.5V range when V<sub>CC</sub> is present to ensure the reliability of the device.

#### **Amplifier Bias Current**

The MAX2057 integrates a two-stage amplifier to simultaneously provide high gain and high IP3. Optimal performance is obtained when R1 and R2 are equal to 1.2k $\Omega$  and 2k $\Omega$ , respectively. The typical supply current is 180mA and the typical output IP3 is 37dBm under these conditions.

Increasing R<sub>1</sub> and R<sub>2</sub> from the nominal values of  $1.2k\Omega$ and  $2k\Omega$  reduces the bias current of each amplifier stage, which reduces the total power consumption and IP3 of the device. This feature can be utilized to further decrease power consumption for applications that do not require high IP3.

#### **Layout Considerations**

A properly designed PC board is an essential part of any RF/microwave circuit. Keep RF signal lines as short as possible to reduce losses, radiation, and inductance. For best performance, route the ground-pin traces directly to the exposed pad underneath the package. This pad **MUST** be connected to the ground plane of the board by using multiple vias under the device to provide the best RF and thermal conduction path. Solder the exposed pad on the bottom of the device package to a PC board exposed pad.

#### **Power-Supply Bypassing**

Proper voltage-supply bypassing is essential for highfrequency circuit stability. Bypass each V<sub>CC</sub> pin with capacitors placed as close to the device as possible. Place the smallest capacitor closest to the device. Refer to the MAX2057 evaluation kit data sheet for more details.

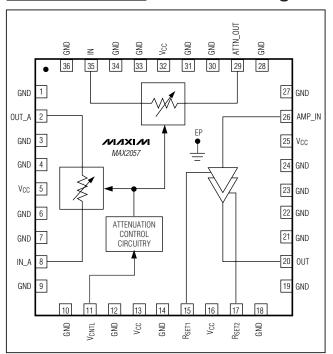
#### Exposed Pad RF and Thermal Considerations

The EP of the MAX2057's 36-pin thin QFN-EP package provides a low-thermal-resistance path to the die. It is important that the PC board on which the IC is mounted be designed to conduct heat from this contact. In addition, the EP provides a low-inductance RF ground path for the device.

The EP **MUST** be soldered to a ground plane on the PC board either directly or through an array of plated via holes. Soldering the pad to ground is also critical for efficient heat transfer. Use a solid ground plane wherever possible.



#### Pin Configuration/ Functional Diagram



PROCESS: BICMOS

## Chip Information

## Package Information

For the latest package outline information and land patterns, go to **www.maxim-ic.com/packages**. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE	PACKAGE	OUTLINE	LAND
TYPE	CODE	NO.	PATTERN NO.
36 TQFN-EP	T3666+2	<u>21-0141</u>	<u>90-0049</u>

## **Revision History**

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	1/05	Initial release	—
1	12/10	Updated General Description, Features, Applications, Ordering Information, DC Electrical Characteristics, AC Electrical Characteristics, Detailed Description, and Analog Attenuation Control sections, and added Recommended AC Operating Conditions section	1, 2, 3, 10, 11

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**MAX2057** 

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